

NPN SILICON EPITAXIAL TRANSISTOR FOR HIGH-SPEED SWITCHING

The 2SC4551 is a power transistor developed for high-speed switching and features low $V_{CE(sat)}$ and high h_{FE} . This transistor is ideal for use in drivers such as DC/DC converters and actuators.

In addition, a small resin-molded insulation type package contributes to high-density mounting and reduction of mounting cost.

FEATURES

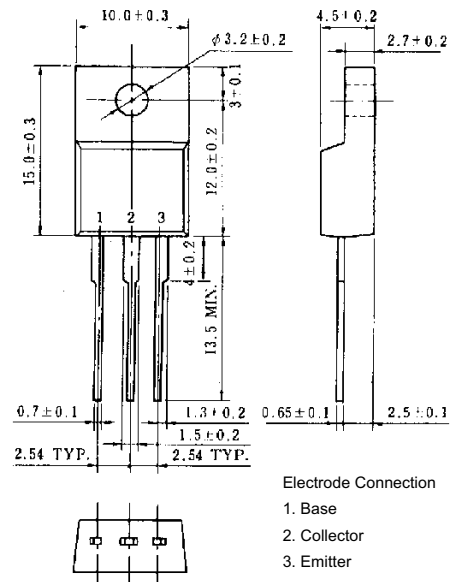
- High h_{FE} and low $V_{CE(sat)}$:
 $h_{FE} \geq 100$ ($V_{CE} = 2\text{ V}$, $I_C = 2\text{ A}$)
 $V_{CE(sat)} \leq 0.3\text{ V}$ ($I_C = 6\text{ A}$, $I_B = 0.3\text{ A}$)
- Mold package that does not require an insulating board or insulation bushing

ABSOLUTE MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Ratings | Unit |
|------------------------------|------------------------------------|-------------|------------------|
| Collector to base voltage | V_{CBO} | 100 | V |
| Collector to emitter voltage | V_{CEO} | 60 | V |
| Emitter to base voltage | V_{EBO} | 7.0 | V |
| Collector current (DC) | $I_{C(DC)}$ | 10 | A |
| Collector current (pulse) | $I_{C(pulse)^*}$ | 20 | A |
| Base current (DC) | $I_{B(DC)}$ | 5.0 | A |
| Total power dissipation | P_T ($T_c = 25^\circ\text{C}$) | 30 | W |
| Total power dissipation | P_T ($T_a = 25^\circ\text{C}$) | 2.0 | W |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

* $PW \leq 300\ \mu\text{s}$, duty cycle $\leq 10\%$

PACKAGE DRAWING (UNIT: mm)



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 Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

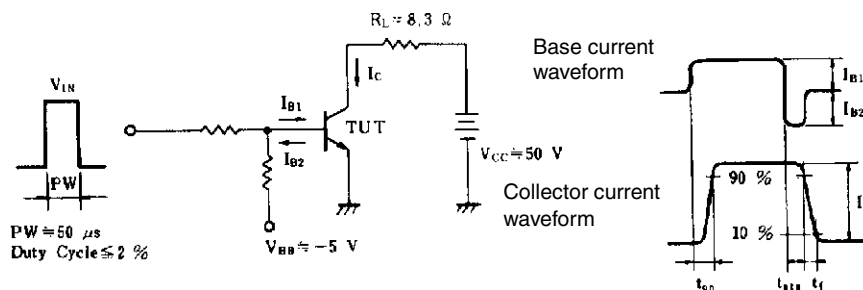
| Parameter | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|------------------------------|------------------|---|------|------|------|---------------|
| Collector to emitter voltage | $V_{CE0(SUS)}$ | $I_C = 6.0\text{ A}, I_B = 0.6\text{ A}, L = 1\text{ mH}$ | 60 | | | V |
| Collector to emitter voltage | $V_{CEX(SUS)}$ | $I_C = 6.0\text{ A}, I_{B1} = -I_{B2} = 0.6\text{ A}, V_{BE(OFF)} = -1.5\text{ V}, L = 180\text{ }\mu\text{H}, \text{ clamped}$ | 60 | | | V |
| Collector cutoff current | I_{CBO} | $V_{CB} = 60\text{ V}, I_E = 0$ | | | 10 | μA |
| Collector cutoff current | I_{CER} | $V_{CE} = 60\text{ V}, R_{BE} = 50\text{ }\Omega, T_a = 125^\circ\text{C}$ | | | 1.0 | mA |
| Collector cutoff current | I_{CEX1} | $V_{CE} = 60\text{ V}, V_{BE(OFF)} = -1.5\text{ V}$ | | | 10 | μA |
| Collector cutoff current | I_{CEX2} | $V_{CE} = 60\text{ V}, V_{BE(OFF)} = -1.5\text{ V}, T_a = 125^\circ\text{C}$ | | | 1.0 | mA |
| Emitter cutoff current | I_{EBO} | $V_{EB} = 5.0\text{ V}, I_C = 0$ | | | 10 | μA |
| DC current gain | h_{FE1}^* | $V_{CE} = 2.0\text{ V}, I_C = 1.0\text{ A}$ | 100 | | | |
| DC current gain | h_{FE2}^* | $V_{CE} = 2.0\text{ V}, I_C = 2.0\text{ A}$ | 100 | 200 | 400 | |
| DC current gain | h_{FE3}^* | $V_{CE} = 2.0\text{ V}, I_C = 6.0\text{ A}$ | 60 | | | |
| Collector saturation voltage | $V_{CE(sat)1}^*$ | $I_C = 6.0\text{ A}, I_B = 0.3\text{ A}$ | | | 0.3 | V |
| Collector saturation voltage | $V_{CE(sat)2}^*$ | $I_C = 8.0\text{ A}, I_B = 0.4\text{ A}$ | | | 0.5 | V |
| Base saturation voltage | $V_{BE(sat)1}^*$ | $I_C = 6.0\text{ A}, I_B = 0.3\text{ A}$ | | | 1.2 | V |
| Base saturation voltage | $V_{BE(sat)2}^*$ | $I_C = 8.0\text{ A}, I_B = 0.4\text{ A}$ | | | 1.5 | V |
| Collector capacitance | C_{ob} | $V_{CB} = 10\text{ V}, I_E = 0, f = 1.0\text{ MHz}$ | | 150 | | pF |
| Gain bandwidth product | f_T | $V_{CE} = 10\text{ V}, I_C = 1.0\text{ A}$ | | 140 | | MHz |
| Turn-on time | t_{on} | $I_C = 6.0\text{ A}, R_L = 8.3\text{ }\Omega, I_{B1} = -I_{B2} = 0.3\text{ A}, V_{CC} \equiv 50\text{ V}$ Refer to the test circuit. | | | 0.3 | μs |
| Storage time | t_{stg} | | | | 1.5 | μs |
| Fall time | t_f | | | | 0.3 | μs |

* Pulse test $PW \leq 350\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

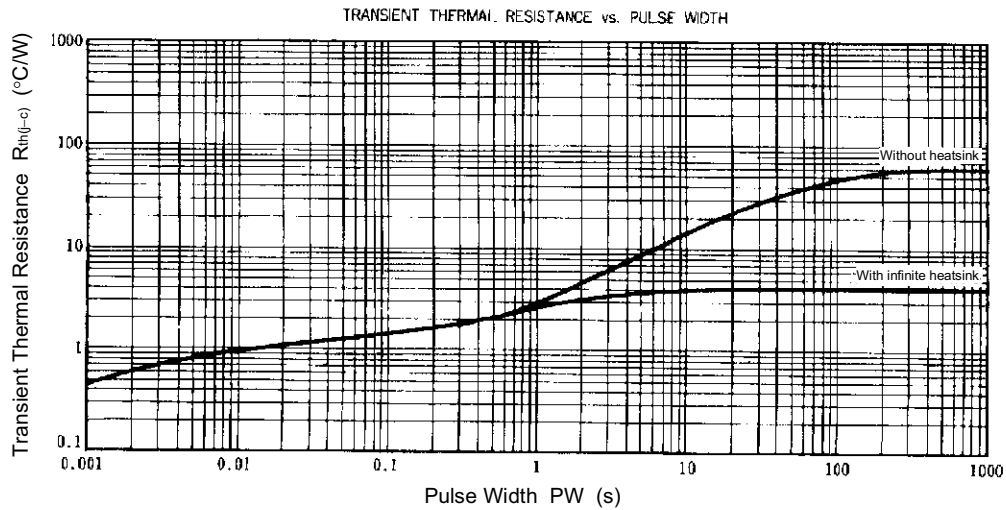
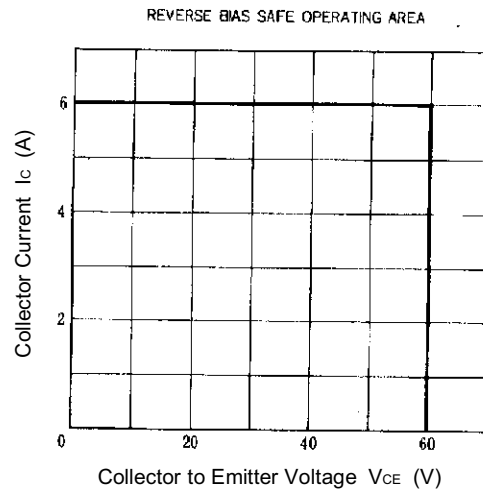
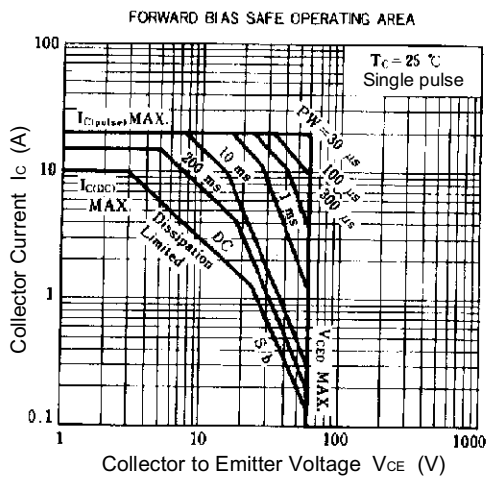
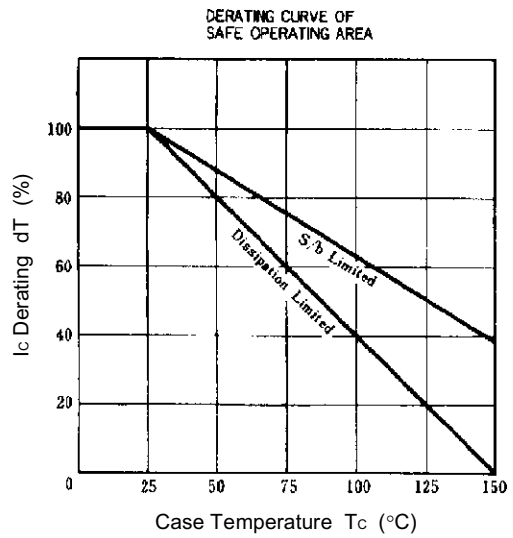
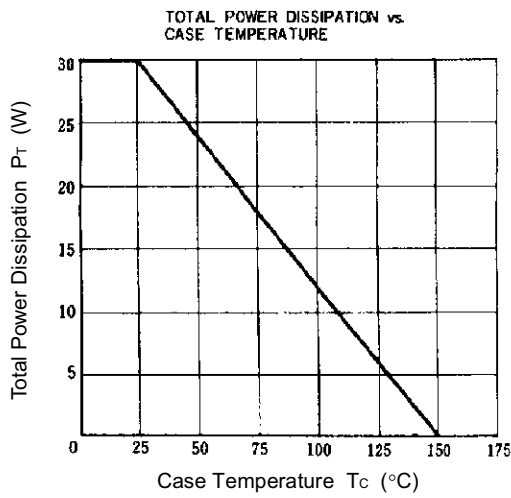
hFE CLASSIFICATION

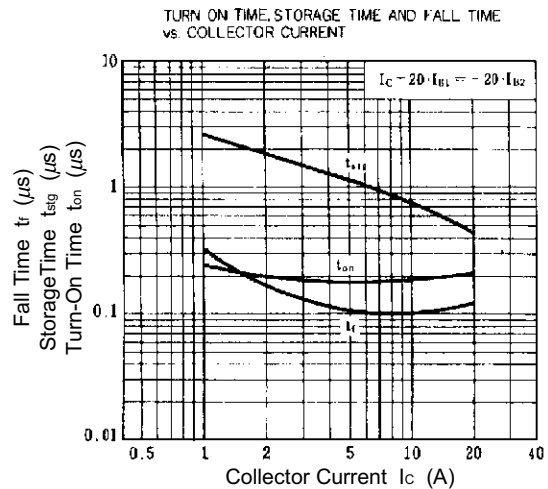
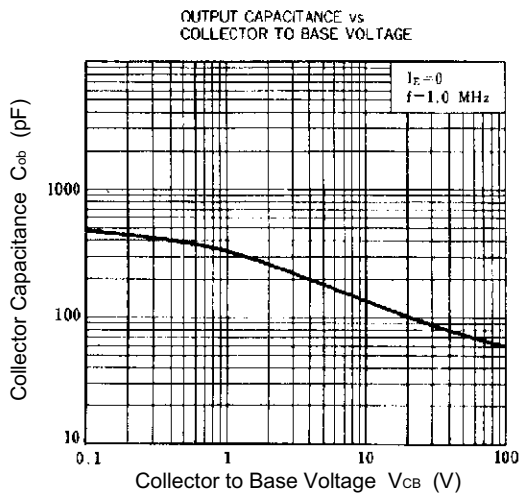
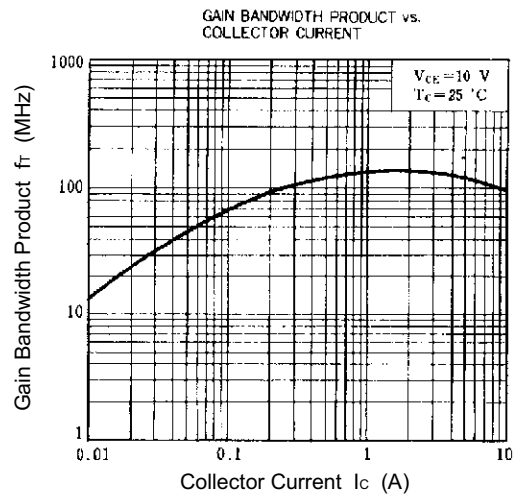
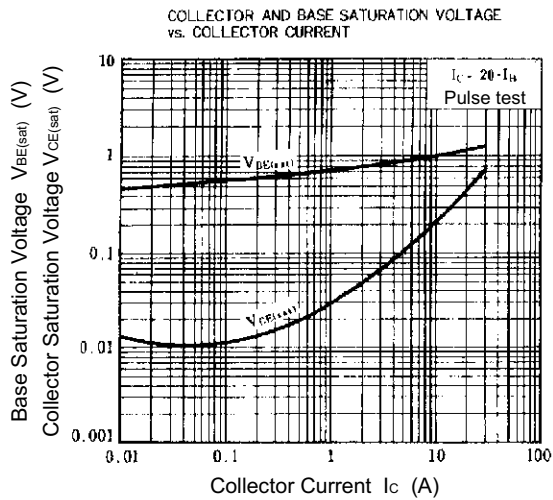
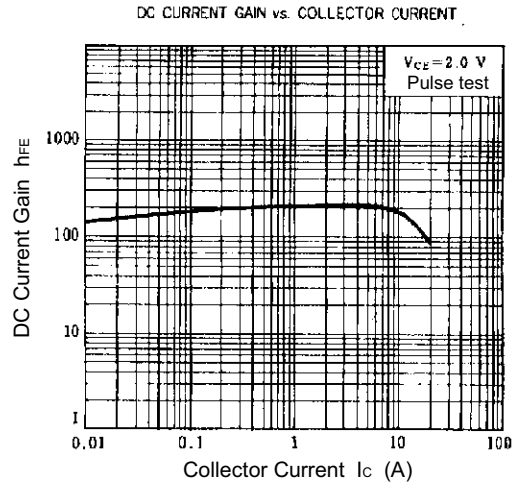
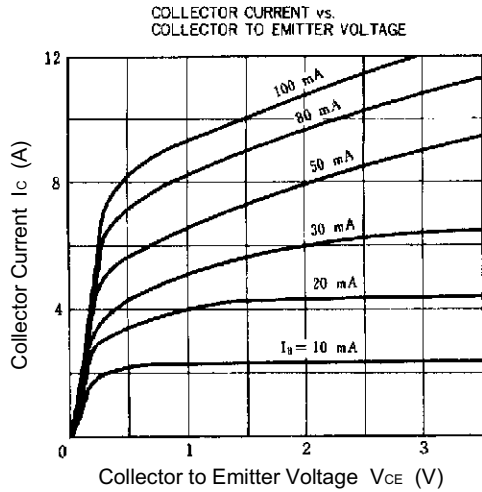
| Marking | M | L | K |
|-----------|------------|------------|------------|
| h_{FE2} | 100 to 200 | 150 to 300 | 200 to 400 |

SWITCHING TIME (t_{on} , t_{stg} , t_f) TEST CIRCUIT



TYPICAL CHARACTERISTICS (Ta = 25°C)





[MEMO]

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